

High-Temperature Thermal Performance & Conductivity Curve of Woqin Silica Aerogel (Up to 600° C)

No.	Test Item	Test Basis	Indicator Requirement	Test Result	Individual Judgment	
1	Thermal Conductivity W/ (m·K)	Avg. Temp. 25°C	GB/T10295-2008	0.021	0.01955	Compliant
2		Avg. Temp. 100°C	GB/T10294-2008	\	0.02228	\
3		Avg. Temp. 200°C		0.028	0.02445	Compliant
4		Avg. Temp. 300°C		0.034	0.03347	Compliant
5		Avg. Temp. 400°C		0.043	0.04259	Compliant
6		Avg. Temp. 500°C		0.068	0.06716	Compliant
7		Avg. Temp. 600°C		0.088	0.08679	Compliant

$$\lambda (T) = 9.499 \times 10^{-11} \cdot T^3 + 1.513 \times 10^{-7} \cdot T^2 - 1.283 \times 10^{-5} \cdot T + 0.02055$$

$$R^2 = 0.9936 \quad (25^\circ \text{C} \leq T \leq 600^\circ \text{C})$$

